

## OT2-SCANGe071-T3

Rev: 15.2

Date	2021.06.28
Language	English
SDS	950612



## SUMMARY

Pb-free - Low Silver, latest technology No-Clean solder paste - Anti tombstoning - Halide/Halogen free

PASTE	OT2-SCANGe071-T3
<b>PROCESS</b>	
No-Clean process	9
Post-solder cleaning	9

INDUSTRY APPLICATION	
Standard electronics	8
Industrial electronics	9
Hi-Rel electronics (automotive)	8

PROCESS CAPABILITY	
Squeegee	9
ProFlow	TBD
Pb-free Profile Air, short	9
Pb-free Profile Air, long	9
Pb-free process N2	9
Vapor phase process	8
Shiny joint appearance	6
Cosmetic cleanliness	9
ICCT compatible	9
Conformal coating	8

Legend	
<i>Especially made for this purpose</i>	9 - 10
<i>Generally qualified for this purpose</i>	7 - 8
<i>Generally usable, but not the best choice</i>	5 - 6
<i>Generally not usable for this purpose</i>	3 - 4
<i>Wrong choice</i>	1 - 2

Check material compatibility with every process change!

Industrial chemical product.

Read MSDS before use.

## Disclaimer:

The information given in this publication has been worked up to the best of the knowledge of Cobar as well as taking into consideration the applicable laws and regulations. We cannot anticipate all conditions under which this information and our products or the products of other manufacturers in combination with our products may be used. We accept no responsibility for results obtained by the application of this information or the safety and suitability of our products alone or in combination with other products. Users are advised to make their own tests to determine the safety and suitability of each such product or product combination for their own purposes. Unless otherwise agreed in writing, we sell the products without warranty, and buyers and users assume all responsibility and liability for loss or damage arising from the handling and use of our products, whether used alone or in combination with other products.

CLASSIFICATION	
DIN-EN-29454-1: 1994	1.1.3.C
IPC-J-STD-004-A: 2004	ROL0
IPC-J-STD-005: 1995 (Powder)	T3
Particle size	[µm] 25-45

PROPERTIES	
Flux code	OT2
Alloy Code	SCANGe071
Alloy composition	Sn98.3Cu0.7Ag1NiGe
Liquidus	[°C] 225
Solidus	[°C] 217
Recommended peak temp.	[°C] 232-260
Acid number	[mg KOH/g] 139.5
Flux	[% w/w] 12.1
Residues	Colorless
Tackiness Malcom TK1	JIS-Z-3284 [gf] @ 0h 120

TEST REPORTS	
IPC/ANSI-J-STD-005	Compliant
Certificate of Compliance	Website
RoHS Compliant	Available
Application Note	EN/DE
Copper Mirror	IPC-TM-650 2.3.32 Pass
Halides	IPC-TM-650 2.3.33 [Silver Chromate] Pass
Halide	IPC-TM-650 2.3.35.1 [Fluoride by Spot] Pass
Copper Corrosion	IPC-TM-650 2.6.15 Pass
SIR	IPC-TM-650 2.6.3.3 Pass
ECM	IPC-TM-650 2.6.14.1 Pass

PACKAGING AND STORAGE	
Packaging jar	PP [g] 500
Packaging cartridge	HDPE [g] 650
Packaging cartridge	HDPE [g] 1300
Packaging Cassette Pro-Flow	[g] 800
Minimum shelf-life in months	4-10 °C 12